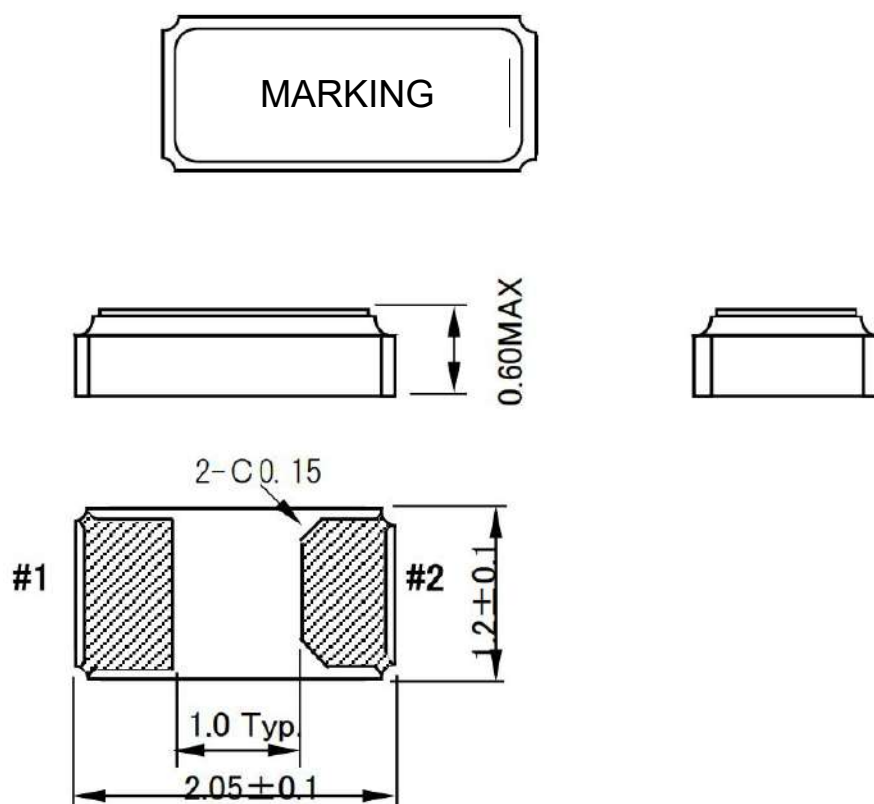


1. QUARTZ CRYSTAL UNIT SPECIFICATION

1.1 Frequency:	32.768KHz
1.2 Holder Type :	SMD2.0×1.2mm
1.3 Frequency Tolerance :	±20ppm at 25°C
1.4 Equivalent Resistance :	80KΩ max.
1.5 Operating Temperature Range :	-40°C To +85°C
1.6 Storage Temperature Range :	-55°C To +125°C
1.7 Temperature Coefficient :	$(-0.03 \pm 10\%) \times 10^{-6}/^{\circ}\text{C}^2$
1.8 Turn-over Temperature :	+25°C±5°C
1.9 Loading Capacitance (CL) :	7pF
1.10 Drive Level :	0.1uW Typical
1.11 Shunt Capacitance (C0) :	1.3pF Typical
1.12 Motional Capacitance (C1) :	6fF Typical
1.13 Q Factor :	13K min.
1.14 Insulation Resistance :	More than 500M ohms
1.15 Aging:	±3 ppm/Year max. Ta=+25°C±3°C, first year
1.16 Dimensions and marking	Refer to page.4
1.17 Emboss carrier tape & reel	Refer to page.5 ~ page.7
1.18 Note	

2. DIMENSIONS (Unit: mm)



c.) Storage condition

Temperature: +40deg.C Max.

Relative Humidity: 80% Max.

d.) Standard packing quantity

3,000PCS / REEL

e.) Material of the tape

Material(Carrier tape) : Black conductive PS

Material (Cover tape) : Clear PE

Material (Reel) : PS

f.) Label contents

.The type of product

.Our specification No.

.Your Part No.

.Lot No.

.Nominal Frequency

.Quantity

.Our Company Name

Sticks label for every reel.

INSPECTION RECORDS

PO NO.:

CUSTOMER P/N:

P/N:

LOT NO.:

PACKAGE:

FREQUENCY:

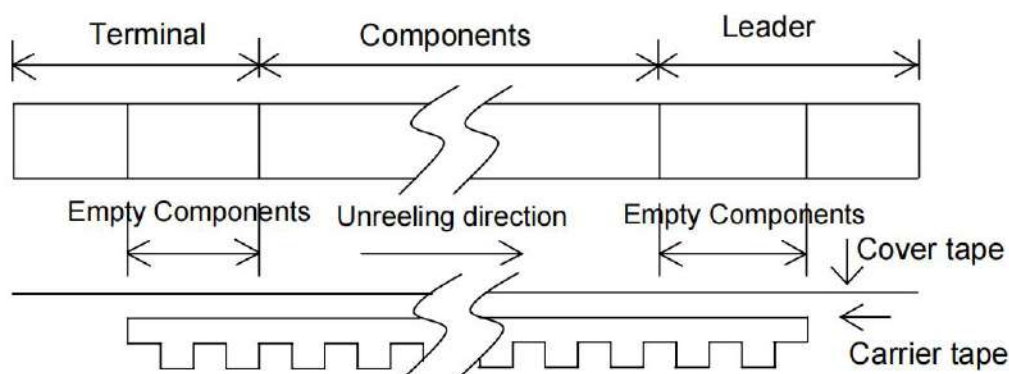
REMARKS:

QUANTITY:

Note: Crystal resonator belongs to non-directional passive components which doesn't have positive and negative poles. So it won't cause effect on usage even been reversed taped on the carrier.

g.) Taping dimension

Leader	Cover-tape	The length of cover-tape in the leader is more than 400 mm including empty embossed area.
	Carrier-tape	After all products were packaged, must remain more than twenty pieces or 400 mm empty area, which should be sealed by cover-tape.
Terminal	Cover-tape	The tip of cover-tape shall be fixed temporary by paper tape and roll around the core of reel one round.
	Carrier-tape	The empty embossed area which are sealed by top cover-tape must remain more the 40 mm.



h.) Joint of tape

The carrier-tape and top cover-tape should not be jointed.

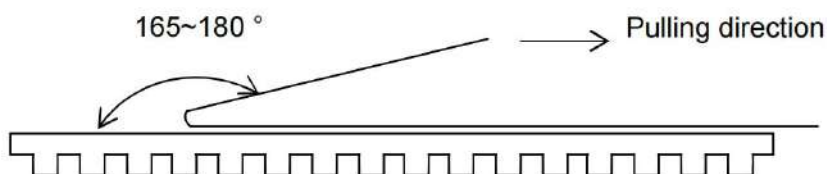
i.) Release strength of cover tape

It has to between 0.1N to 0.7N under following condition.

Pulling direction 165° to 180°

Speed 300mm/min.

Otherwise unless specified.



Other standards shall be based on JIS C 0806-1990.

4. Mechanical Endurance: Provided that measurement shall be carried out after letting it alone in the room temperature for 1 hour.

	Item	Conditions	Specifications
4.1	Drop	Fall freely from 100 cm of height 3 times on a firm wood	MIL-STD-202F-203B
4.2	Mechanical Shock	Device are shocked to half sine wave (1000 G) three mutually perpendicular axes each 3 times.	MIL-STD-202F
4.3	Vibration	(1)Vibration Frequency: 10~55Hz (2)Cycle: 1 to 2 Min. (3)Full Cycle: 1.5mm P-P. (4)Direction: X.Y.Z (5)Time: 2 Hours / Each Direction	MIL-STD-883E
4.4	Substrate Bending	Mount the specimen on substrate. Apply the following pressure Direction: see Fig –1 Speed: 0.5 mm/sec Hours: 5 ± 1 sec Amount of substrate: 3 mm Max.	Without mechanical damage such as breaks. Without electrode peeling. Electrical characteristics shall be satisfied.
4.5	Adhesion	Mount the specimen on substrate. Apply the following pressure Direction: see Fig –2 Weight: 10N Hours: 10 ± 1 sec	
4.6	Body strength	Mount the specimen on substrate. Apply the following pressure Direction: see Fig –3 Weight: 10N Hours: 10 ± 1 sec	
4.7	Seal	Fine Leak: 4.5kgf/cm ² 2hours 1×10 ⁻⁹ Pa.m ³ /sec Gross Leak: 4.5kgf/cm ² 2hours 1.5×10 ⁻⁵ Pa.m ³ /sec	MIL-STD-883E

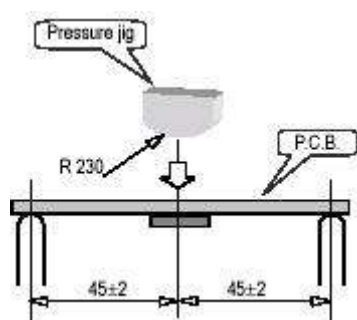


Fig-1

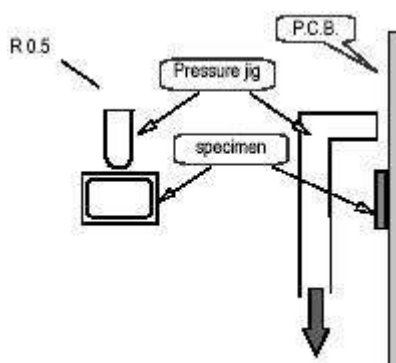


Fig-2

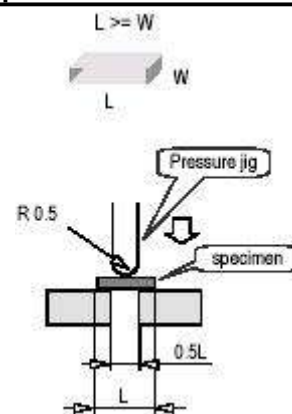
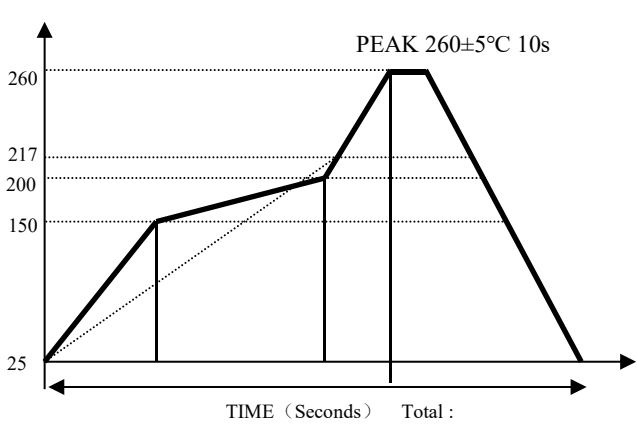


Fig-3

4.8	Solder ability	Pre-heat temperature : $+150\pm 10^{\circ}\text{C}$ Pre-heat time : 60~120s When the temperature of the specimen is reached at $+215\pm 3^{\circ}\text{C}$, it shall be left for $30\pm 1\text{sec.}$ Peak temperature $240\pm 5^{\circ}\text{C}$ Material: Pb-free (Sn-3.0Ag-0.5Cu) Flux : Rosin resin methyl alcohol solvent (1:4) The electrodes should be covered by a new solder at least 90% of immersed area.	MIL-STD-883E 2003												
4.9	Resistance to Soldering Heat	Run in Reflow Reflow soldering shall be allowed Only two(2) time. Available for Lead Free Soldering  <table border="1"> <tbody> <tr> <td>(1)</td><td>Preheat</td><td>160~180 deg.C</td><td>120sec.</td></tr> <tr> <td>(2)</td><td>Primary heat</td><td>220 deg.C</td><td>60sec.</td></tr> <tr> <td>(3)</td><td>Peak</td><td>260 deg.C</td><td>10sec. Max.</td></tr> </tbody> </table>	(1)	Preheat	160~180 deg.C	120sec.	(2)	Primary heat	220 deg.C	60sec.	(3)	Peak	260 deg.C	10sec. Max.	MIL-STD-202F
(1)	Preheat	160~180 deg.C	120sec.												
(2)	Primary heat	220 deg.C	60sec.												
(3)	Peak	260 deg.C	10sec. Max.												

5. Environmental Endurance: Provided that measurement shall be carried out after letting it alone in the room temperature for 1 hour.

	Item	Conditions	Specifications
5.1	Humidity	+60°C±2°C, RH 80~85%, Duration of 500 hours. The units are then allowed to stand for approx 2 hours in room temperature before checking	MIL-STD-202F
5.2	Storage in Low Temperature	Temperature: -40±2°C , Duration of 500 hours. The units are then allowed to stand at room temperature for approx 2 hours before checking.	MIL-STD-883E
5.3	Storage in High Temperature	Temperature: +85°C±2°C, Duration of 500 hours. The units are then allowed to stand at room temperature for approx 2 hours before checking.	MIL-STD-883E
5.4	Thermal Shock	Temperature 1: -40°C±5°C Temperature 2: +85°C±5°C Temperature change between T1 and T2 at soonest Run 100 cycles, maintain T1 and T2 30minutes each in one cycle (Refer to Fig-4)	MIL-STD-883E

